SEMICONDUCTOR DEVICE WITH SMALL DIE PAD AND METHOD OF MAKING SAME

ABSTRACT

Semiconductor device package 53 having a lead frame with a mounting pad 31 smaller than the IC chip 10 mounted thereon, and a method of making a semiconductor device package based on wire bonding using a heater insert 38 with a mounting pad insertion concave part 51. Separation between the mounting pad and an encapsulating resin is eliminated, cracks are not created in the resin, or are considerably reduced, and warpage of the package can be prevented. Also, bonding of wires between leads and respective bonding pads 17 on the chip 10 can be executed stably and efficiently.

Figure 1

This Sheet Has Been Replaced

